

Technology Voucher Programme (TVP)

Title (Reference)	: Quick-Turn Chip-on-Board Wirebonding Process Flow for Mixed-Signal Semiconductors (TVP/0274/18) 快速半導體錫線流程 (TVP/0274/18)
Implementation Schedule (dd/mm/yyyy)	: 02/01/2019 - 01/01/2020
Total Approved Amount	: HK\$200,000.00
Project Coordinator	: Dr Robin Matthew TSANG 曾文立 博士 Engineer & Director, MixSemi Limited Address: Desk#35, 111-113, 1/F, Enterprise Place, No. 5 Science Park West Avenue, Pak Shek Kok, NT Tel: 852-55007655 Email: robin.tsang@mixsemi.com
Applicant Enterprise	: MixSemi Limited 運營科技有限公司
Proposed Technological Solution(s)	: <ul style="list-style-type: none"> • Others: Quick-Turn Wirebonding Process • 其他：Quick-Turn Wirebonding Process

All information above is provided by the company concerned. Please contact the company for more information.